Lasertec

PRESS RELEASE

Lasertec Corporation
2-10-1 Shin-yokohama, Kohoku-ku, Yokohama
(Tokyo Stock Exchange Prime Market, Code 6920)

Lasertec Releases DHIOS Series BS300 Wafer Backside Inspection System

Yokohama, November 27, 2026 – Lasertec Corporation today announced the release of the DHIOS Series BS300, a new inspection system designed to detect particles and defects on the backside of wafers.

Particles present on the backside of wafers or on the stage/chuck can cause defocus and overlay errors in EUV lithography processes because they create localized height differences across the wafer surface.

Conventionally, backside wafer inspection has relied on the intensity of scattered light to estimate particle size. However, obtaining information on particle height has been difficult, making it challenging to identify which particles may have critical impact to the lithography process.

To address this challenge, the DHIOS Series BS300 adopts height information as a new inspection index. Based on an entirely new inspection concept and developed using Lasertec's proprietary optical technology, the BS300 enables the simultaneous detection of micro-particles and acquires their height information at high speed. The system can effectively generate particle data that identifies particles that may cause defocus or overlay errors while maintaining high-sensitivity detection of micro-particles.

By effectively detecting particles with height profiles that may cause defocus and overlay errors, the BS300 contributes to the precision of lithography inspection in leading-edge lithography processes.

Lasertec remains committed to delivering innovative inspection solutions for leading-edge semiconductor manufacturing that enhance quality and productivity.

Features

- Particle detection on the backside of wafers that may cause defocus errors
- Simultaneous acquisition of particle detection and height information
- Applicable for particle detection on the frontside surface of wafers

Applications

- Particle control on the backside of wafers during EUV lithography processes



DHIOS Series BS300 Wafer Backside Inspection System

Contact:
Airi Toda
Solution Sales Department I
Lasertec Corporation
Phone: +81(0)45-478-7337
Email: sales@lasertec.co.jp